

## ABSTRACT OF THE DISCLOSURE

A new method has been developed to provide underfill to chips  
5 mounted on substrates. First, an underfill is dispensed on the  
substrate. Second, the bumps of the chip are dipped in a flux  
that does not contain filler. Third, the chip that has been  
dipped in a tacky thermosettable flux is placed on the substrate,  
and fourth, the chip is soldered to the substrate, and  
10 simultaneously the underfill is cured. This process eliminates  
the interference on solder joints caused by the presence of filler  
in filled no-flow underfill. In addition, the fluxing property of  
the flux allows the use of underfills with emphasis on curing and  
mechanical properties instead of fluxing performance. Accordingly,  
15 a mounted device with reliable solder joints and underfill  
encapsulation is obtained.

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